Eight ('388) or Sixteen ('386) Line Receivers Meet or Exceed the Requirements of ANSI **TIA/EIA-644 Standard**

- Integrated 110- Ω Line Termination **Resistors on LVDT Products**
- Designed for Signaling Rates[†] Up To 630 Mbps
- SN65 Version's Bus-Terminal ESD Exceeds 15 kV
- **Operates From a Single 3.3-V Supply**
- Typical Propagation Delay Time of 2.6 ns •
- Output Skew 100 ps (Typ) Part-To-Part Skew is Less Than 1 ns
- LVTTL Levels are 5-V Tolerant
- **Open-Circuit Fail Safe** •
- **Flow-Through Pin Out**
- Packaged in Thin Shrink Small-Outline • Package With 20-mil Terminal Pitch

description

The 'LVDS388 and 'LVDT388 (T designates integrated termination) are eight and the 'LVDS386 and 'LVDT386 sixteen differential line receivers respectively that implement the electrical characteristics of low-voltage differential signaling (LVDS). This signaling technique lowers the output voltage levels of 5-V differential standard levels (such as EIA/TIA-422B) to reduce the power, increase the switching speeds, and allow operation with a 3-V supply rail. Any of the eight or sixteen differential receivers will provide a valid logical output state with a ±100 mV differential input voltage within the input commonmode voltage range. The input common-mode voltage range allows 1 V of ground potential difference between two LVDS nodes. Additionally, the high-speed switching of LVDS signals almost always require the use of a line impedance matching resistor at the receiving end of the cable or transmission media. The LVDT products eliminate this external resistor by integrating it with the receiver.

SN65LVDS388, SN75LVDS388 SN65LVDT388, SN75LVDT388 DBT PACKAGE (TOP VIEW)			SN65LVE	DT386,	SN75LVDS386 SN75LVDT386 CKAGE /IEW)
A1A 1 0 A1B 2 A2A 3 A2B 4 NC 5 B1A 6 B1B 7 B2A 8 B2B 9 NC 10 C1A 11	34 33 32 31 30 29 28	GND V _{CC} ENA A1Y A2Y ENB B1Y B2Y GND V _{CC} GND	A1A A1B A2A A2B A3A A3B A4B B1A B1B B2A	5 6 7 8 9 10 11	64 GND 63 V _{CC} 62 V _{CC} 61 GND 60 ENA 59 A1Y 58 A2Y 57 A3Y 56 A4Y 55 ENB 54 B1Y
C1B 12 C2A 13 C2B 14 NC 15 D1A 16 D1B 17 D2A 18 D2B 19	26 25 24 23	C1Y C2Y ENC D1Y D2Y END V _{CC} GND	B2B L B3A L B3B L B4A L B4B L C1A L C1A L C2A L C2B L	13 14 15 16 17 18 19	53 B2Y 52 B3Y 51 B4Y 50 GND 49 V _{CC} 48 V _{CC} 47 GND 46 C1Y 45 C2Y

(TOP VIEW)					
1				1	
A1A	1	U	64	GND	
A1B	2		63	Vcc	
A2A	3		62	V _{CC}	
A2B	4		61	GND	
АЗАЦ	5		60	ENA	
АЗВ 🛛	6		59	A1Y	
A4A	7		58	A2Y	
A4B	8		57	A3Y	
B1A	9		56	A4Y	
B1B	10		55	ENB	
B2A	11		54	B1Y	
в2в 🛛	12			B2Y	
вза 🛛	13			B3Y	
взв 🛛	14		51	B4Y	
в4А [15		50	GND	
в4в 🛛	16		49	Vcc	
C1A	17		48	Vcc	
С1В	18		47	GND	
C2A	19		46	C1Y	
C2B	20		45	LC2Y	
СЗА	21		44	СЗҮ	
СЗВ 🛛	22		43	C4Y	
C4A	23		42	ENC	
С4В	24		41	D1Y	
D1A	25		40	D2Y	
D1B	26		39	D3Y	
D2A	27		38	D4Y	
D2B	28		37	LEND	
D3A	29		36	L GND	
D3В	30		35	UV _{CC}	
D4A	31		34	lvcc	
D4B	32		33	GND	



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† Signaling rate, 1/t, where t is the minimum unit interval and is expressed in the units bits/s (bits per second)

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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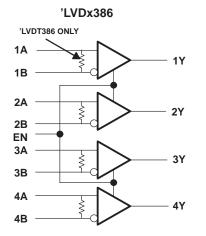
description (continued)

The intended application of this device and signaling technique is for point-to-point baseband data transmission over controlled impedance media of approximately 100 Ω . The transmission media may be printed circuit board traces, backplanes, or cables. The large number of receivers integrated into the same substrate along with the low pulse skew of balanced signaling, allows extremely precise timing alignment of clock and data for synchronous parallel data transfers. When used with its companion, 8- or 16-channel driver, the SN65LVDS389 or SN65LVDS387, over 300 million data transfers per second in single-edge clocked systems are possible with very little power. (Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other system characteristics.)

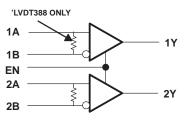
	-		
Part number	Temperature Range	Number of Receivers	Bus-Pin ESD
SN65LVDS386DGG	–40°C to 85°C	16	15 kV
SN65LVDT386DGG	–40°C to 85°C	16	15 kV
SN75LVDS386DGG	0°C to 70°C	16	4 kV
SN75LVDT386DGG	0°C to 70°C	16	4 kV
SN65LVDS388DBT	–40°C to 85°C	8	15 kV
SN65LVDT388DBT	–40°C to 85°C	8	15 kV
SN75LVDS388DBT	0°C to 70°C	8	4 kV
SN75LVDT388DBT	0°C to 70°C	8	4 kV

Available Options

logic diagram (positive logic)







Function Table

SNx5LVD386/388 and SNx5LVDT386/388						
DIFFERENTIAL INPUT ENABLES OUTPUT						
A-B	EN	Y				
$V_{ID} \ge 100 \text{ mV}$	Н	Н				
-100 mV < $V_{ID} \le 100 \text{ mV}$	Н	?				
V _{ID} ≤ -100 mV	Н	L				
Х	L	Z				
Open	Н	Н				

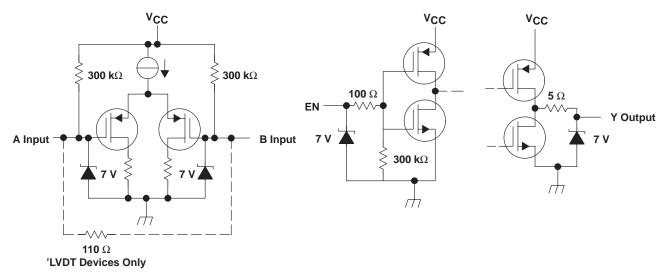
H = high level, L = low level, X = irrelevant,

Z = high impedance (off), ? = indeterminate



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equivalent input and output schematic diagrams



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage rar	nge, V _{CC} (see Note 1)	−0.5 V to 4 V
Voltage range:	Enables or Y	-0.5 V to V _{CC} + 2 V
	A or B	–0.5 V to 4 V
Electrostatic disch	arge: (see Note 2)	
	SN65' (A, B, and GND)	Class 3, A:15 kV, B: 700 V
	SN65' (All pins)	Class 3, A: 8 kV, B:600 V
	SN75' (A, B, and GND)	Class 2, A:4 kV, B: 400 V
	SN75' (All pins)	Class 2, A: 2 kV, B:200 V
Continuous power	dissipation	See Dissipation Rating Table
Storage temperatu	ure range	−65°C to 150°C
Lead temperature	1,6 mm (1/16 in) from case for 10 seconds $% \left(1,1,1,1,1,1,1,1,1,1,1,1,1,1,1,1,1,1,1,$	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

2. Tested in accordance with MIL-STD-883C Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C	DERATING FACTOR [‡] ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
DBT	1071 mW	8.5 mW/°C	688 mW	556 mW
DGG	2094 mW	16.7 mW/°C	1342 mW	1089 mW

[‡]This is the inverse of the junction-to-ambient thermal resistance when board-mounted (low-k) and with no air flow.



recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		3	3.3	3.6	V
High-level input voltage, V _{IH}		2			V
Low-level input voltage, VIL				0.8	V
Magnitude of differential input voltage, VID		0.1		0.6	V
Common-mode input voltage, VIC (see Figure 4)		$\frac{ V_{ D} }{2}$	2.4	$4 - \frac{ V_{ D} }{2}$	V
			V	′CC – 0.8	
Operating free-air temperature, TA	SN75'	0		70	°C
	SN65'	-40		85	°C



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electrical characteristics over recommended operating conditions (unless otherwise noted).

	PARAMETER		TEST CO	NDITIONS	MIN	TYP [†]	MAX	UNIT
VITH+	H+ Positive-going differential input voltage threshold		See Figure 1 and Table 1				100	mV
V _{ITH-}	Negative-going differential input voltage thre	shold	See Figure 1 an		-100			mV
VOH	High-level output voltage		I _{OH} = –8 mA		2.4	3		V
Vol	Low-level output voltage		I _{OL} = 8 mA			0.2	0.4	V
	Supply current		Enabled,	No load		50	70	mA
ICC	Supply current	_	Disabled				3	IIIA
		'LVDS	$V_{I} = 0 V$			-13	-20	
	Input current (A or B inputs)	LVDS	V _I = 2.4 V		-1.2	-3		μA
II Input curre	input current (A or B inputs)	'LVDT	V _I = 0 V, other in	nput open	-40		-40	μΛ
			V _I = 2.4 V, other	r input open	-2.4			
IID	Differential input current I _{IA} – I _{IB}	'LVDS		V _{IB} = 0.1V, V _{IB} = 2.3 V			±2	μΑ
IID	Differential input current (I _{IA} – I _{IB})	'LVDT	V _{IA} = 0.2 V, V _{IA} = 2.4 V,	V _{IB} = 0V, V _{IB} = 2.2 V	1.5		2.2	mA
II(OFF)	Power-off Input current (A or B inputs)	'LVDS	$V_{CC} = 0 V,$	Vj=2.4 V		12	±20	μA
II(OFF)	Power-off Input current (A or B inputs)	'LVDT	$V_{CC} = 0 V,$	Vj=2.4 V			±40	μA
IIН	High-level input current (enables)		V _{IH} = 2 V				10	μA
۱ _{IL}	Low-level input current (enables)		V _{IL} = 0.8 V				10	μA
1			VO = 0 V			±1	<u>^</u>	
IOZ High–impedance output current			V _O = 3.6 V				10	μA
C _{IN}	Input Capacitance, A or B input to GND		V _{ID} = 0.4 sin 2.	5E09 t V		5		pF
Z _(t)	Termination impedance		$V_{ID} = 0.4 \sin 2.4$	5E09 t V	88		132	Ω

[†] All typical values are at 25°C and with a 3.3 V supply.

switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	түр†	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output		1	2.6	4	ns
^t PHL	Propagation delay time, high-to-low-level output		1	2.5	4	ns
t _r	Differential output signal rise time		500	800	1200	ps
t _f	Differential output signal fall time	See Figure 2	500	800	1200	ps
^t sk(p)	Pulse skew (tpHL - tpLH)	1		150	600	ps
^t sk(o)	Output skew [‡]			100	400	ps
^t sk(pp)	Part-to-part skew§	7			1	ns
^t PZH	Propagation delay time, high-impedance-to-high-level output			7	15	ns
t _{PZL}	Propagation delay time, high-impedance-to-low-level output			7	15	ns
^t PHZ	Propagation delay time, high-level-to-high-impedance output	See Figure 3		7	15	ns
^t PLZ	Propagation delay time, low-level-to-high-impedance output			7	15	ns

[†] All typical values are at 25°C and with a 3.3 V supply. [‡] t_{sk(o)} is the magnitude of the time difference between the t_{PLH} or t_{PHL} of all drivers of a single device with all of their inputs connected together. \$ tsk(pp) is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.



PARAMETER MEASUREMENT INFORMATION

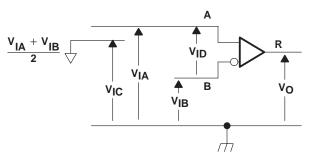


Figure 1. Voltage Definitions

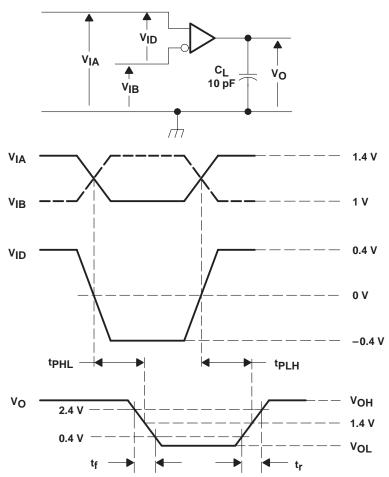
Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages

Applied Vo	Itages	Resulting Differential Input Voltage	Resulting Common– Mode Input Voltage
VIA	VIB	V _{ID}	V _{IC}
1.25 V	1.15 V	100 mV	1.2 V
1.15 V	1.25 V	–100 mV	1.2 V
2.4 V	2.3 V	100 mV	2.35 V
2.3 V	2.4 V	–100 mV	2.35 V
0.1 V	0 V	100 mV	0.05 V
0 V	0.1 V	–100 mV	0.05 V
1.5 V	0.9 V	600 mV	1.2 V
0.9 V	1.5 V	–600 mV	1.2 V
2.4 V	1.8 V	600 mV	2.1 V
1.8 V	2.4 V	–600 mV	2.1 V
0.6 V	0 V	600 mV	0.3 V
0 V	0.6 V	–600 mV	0.3 V



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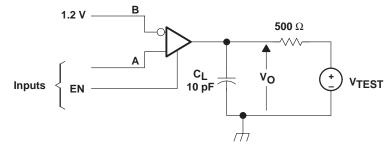


NOTE: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, Pulse Repetition Rate (PRR) = 50 Mpps, Pulse width = 10 ± 0.2 ns . C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 2. Timing Test Circuit and Wave Forms



PARAMETER MEASUREMENT INFORMATION



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

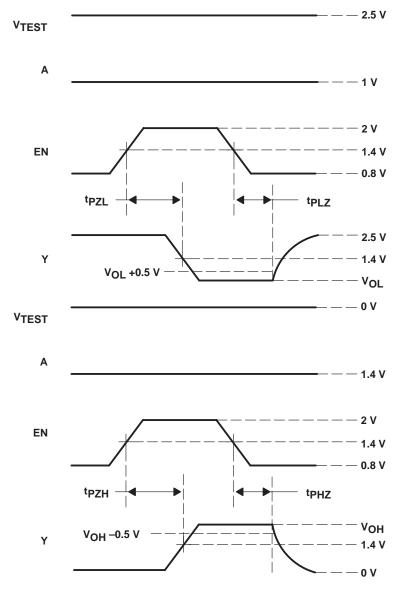
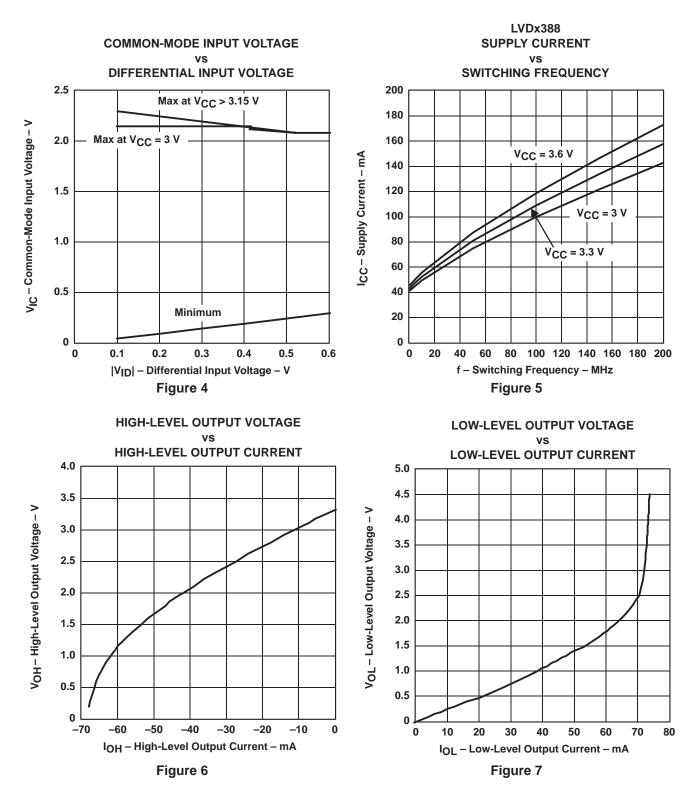


Figure 3. Enable/Disable Time Test Circuit and Wave Forms



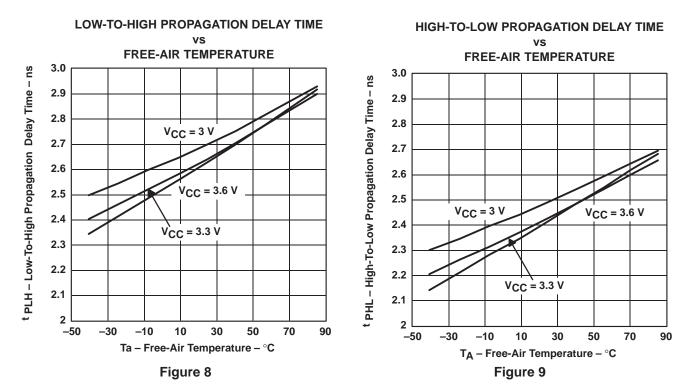
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TYPICAL CHARACTERISTICS

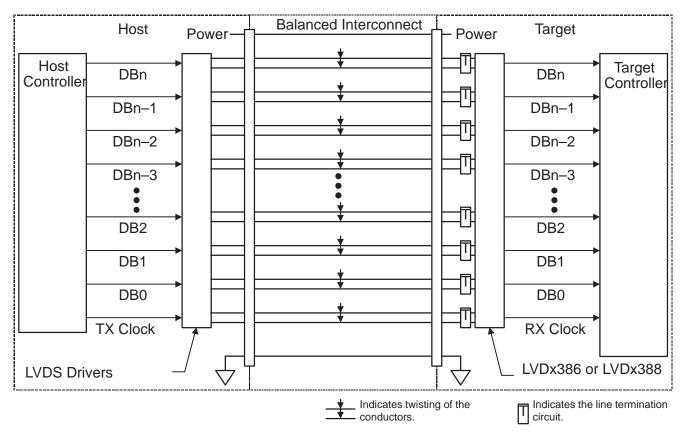


TYPICAL CHARACTERISTICS





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APPLICATION INFORMATION

Figure 10. Typical Application Schematic



APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different in how it handles the open-input circuit situation, however.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver will pull each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 10. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

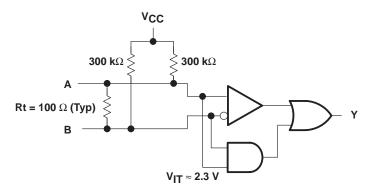


Figure 11. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver will be valid with less than a 100 mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pull-up currents from the receiver and the fail-safe feature.

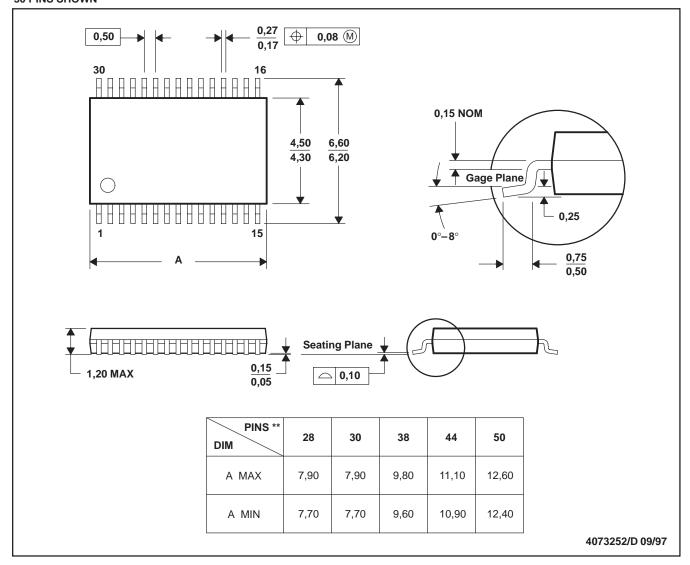


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MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

DBT (R-PDSO-G**) **30 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-153



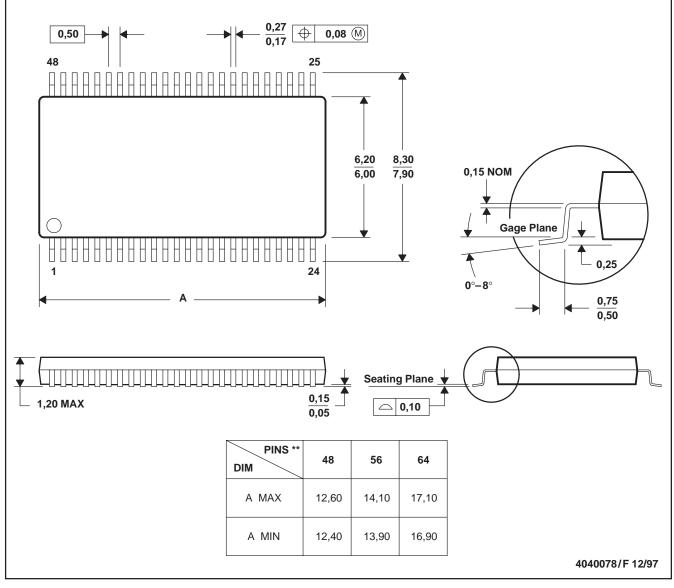
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MECHANICAL DATA

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



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